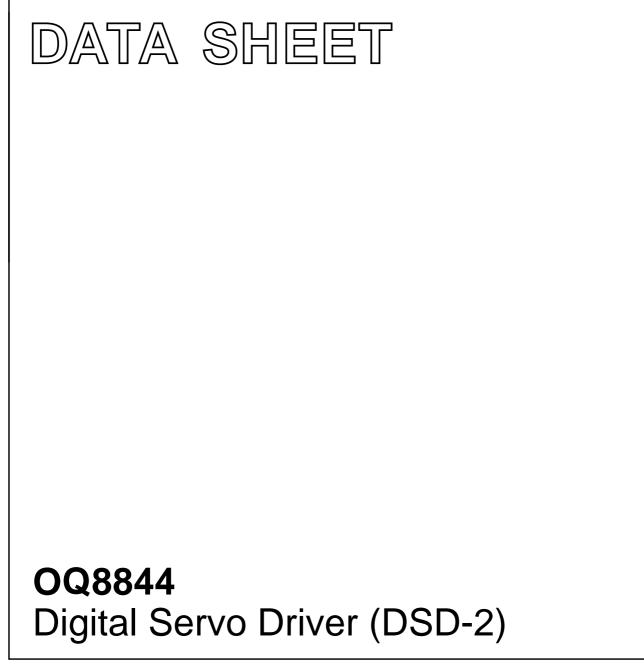
# INTEGRATED CIRCUITS



Product specification File under Integrated Circuits, IC01 1995 Nov 27



HILIP

### FEATURES

#### Servo functions

- 1-bit class-D focus actuator driver (3.3  $\Omega$ )
- 1-bit class-D radial actuator driver (3.7  $\Omega$ )
- 1-bit class-D sledge motor driver (2.5 Ω).

#### Other features

- Supply voltage 5 V only
- Small package (SOT163-1)
- Higher efficiency, compared with conventional drivers, due to the class-D principle
- Built-in digital notch filters for higher efficiency
- Enable input for focus and radial driver
- Enable input for sledge driver
- Differential outputs for all drivers
- Separate power supply pins for all drivers.

### GENERAL DESCRIPTION

The OQ8844 or Digital Servo Driver 2 (DSD2) consists of 1-bit class-D power drivers, which are specially designed for digital servo applications. Three such amplifiers are integrated in one chip, to drive the focus and radial actuators and the sledge motor of a compact disc optical system.

The main benefits of using this principle are its higher efficiency grade compared to conventional analog power amplifiers, its higher integration level, its differential output and the fact that only a few external components are needed. When using these digital power drivers in a digital servo application, the statement 'complete digital servo loop' becomes more realistic.

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V <sub>DDD</sub>	digital supply voltage	4.5	-	5.5	V
V <sub>DD(F)</sub>	supply voltage focus actuator	4.5	_	5.5	V
V <sub>DD(R)</sub>	supply voltage radial actuator	4.5	-	5.5	V
V <sub>DD(S)</sub>	supply voltage sledge actuator	4.5	-	5.5	V
I <sub>DDDq</sub>	quiescent supply current digital part	-	-	10	μA
I <sub>DD(F)</sub>	supply current focus	-	126	250	mA
I <sub>DD(R)</sub>	supply current radial	-	20	250	mA
I <sub>DD(S)</sub>	supply current sledge	-	150	560	mA
f <sub>i(clk)</sub>	input clock frequency	-	4.2336	5	MHz
P <sub>tot</sub>	total power dissipation	-	110	-	mW
T <sub>amb</sub>	operating ambient temperature	-40	-	+85	°C

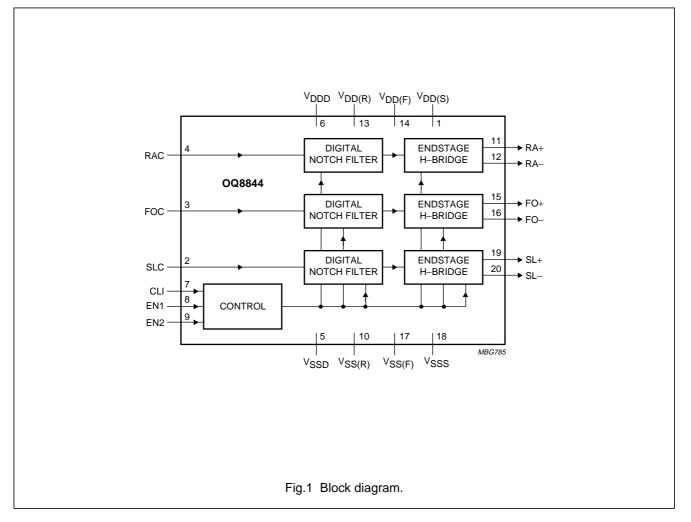
### **ORDERING INFORMATION**

TYPE		PACKAGE			
NUMBER	BER NAME DESCRIPTION V		VERSION		
OQ8844	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1		

#### QUICK REFERENCE DATA

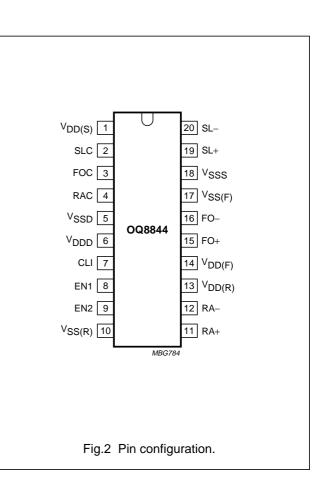
### OQ8844

### **BLOCK DIAGRAM**



### PINNING

SYMBOL	PIN	DESCRIPTION
V <sub>DD(S)</sub>	1	supply voltage for sledge motor driver
SLC	2	PDM input for sledge driver
FOC	3	PDM input for focus driver
RAC	4	PDM input for radial driver
V <sub>SSD</sub>	5	digital ground
V <sub>DDD</sub>	6	digital supply voltage
CLI	7	clock input
EN1	8	enable input 1
EN2	9	enable input 2
V <sub>SS(R)</sub>	10	radial driver ground
RA+	11	radial driver (positive output)
RA–	12	radial driver (negative output)
V <sub>DD(R)</sub>	13	radial supply voltage
V <sub>DD(F)</sub>	14	focus supply voltage
FO+	15	focus driver (positive output)
FO-	16	focus driver (negative output)
V <sub>SS(F)</sub>	17	focus ground
V <sub>SSS</sub>	18	sledge driver ground
SL+	19	sledge driver (positive output)
SL-	20	sledge driver (negative output)



#### FUNCTIONAL DESCRIPTION

#### Principle of a class-D digital power driver

Figure 3 shows the block diagram of one of the digital drivers integrated in the DSD2. It consists of a timing block and four CMOS switches. The input signal is a 1-bit Pulse Density Modulated (PDM) signal, the output of the digital servo ICs.

The maximum operating clock frequency of the device is 5 MHz. With the mentioned digital servo ICs, the operating frequency of the digital drivers is 4.2336 MHz ( $96 \times 44.1$  kHz). The sampling frequency of the 1-bit code however is 1.0584 MHz, so internally in the DSD2 the clock speed of the switches will be 1.0584 MHz. The higher input clock frequency is used to make non-overlapping pulses to prevent short-circuits between the supply voltages. For the control of the switches, two states can be distinguished. If the 1-bit code contains a logic 1, switches A and D are closed and current will flow in the direction as shown in Fig.4.

If the 1-bit code contains a logic 0, switches B and C are closed and current will flow in the opposite direction, as shown in Fig.5.

This indicates that the difference between the mean number of ones and zeros in the PDM signal determines the direction in which the actuator or motor will rotate.

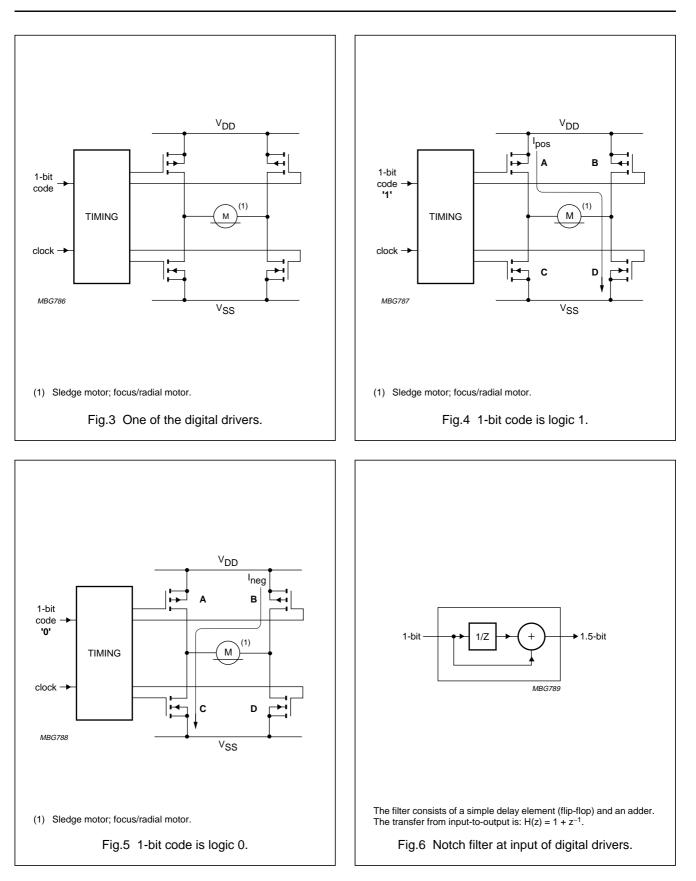
If the mean number of ones and zeros is equal (Idle mode) the current through the motor or actuator is alternated between the positive and negative direction at a speed of half the sample frequency of 1.0584 MHz. This results in a high dissipation and the motor does not move.

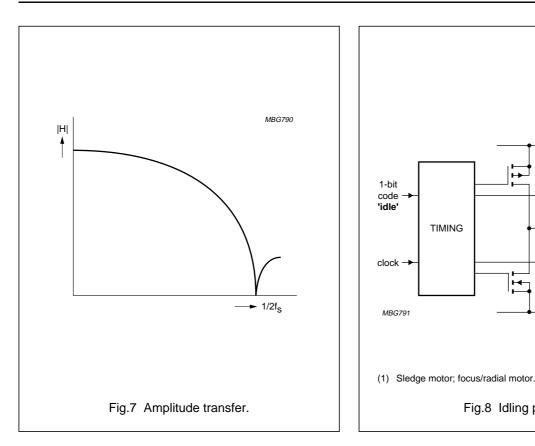
To improve the efficiency, a digital notch filter is added at the input of the digital drivers. This filters the Idle mode pattern (1010101010 etc.) see Fig.6.

The amplitude transfer as a function of frequency is given in Fig.7.

Figure 7 shows that the filter has a zero on  $\frac{1}{2}f_s$ , consequentially filtering out the idle pattern (101010). The output of this filter is a three-level code (1.5-bit). For the control of the switches three states (1.5-bit) can be distinguished: the two states as described earlier and a third one. This state is used when an idling pattern is supplied.

Switches C and D are closed (see Fig.8). In this idle mode, no current will flow and thus the efficiency will be improved. This mode is also used to short-circuit the inductive actuator/motor. In this way, high induction voltages are prevented because the current can commutate via the filter and the short-circuit in the switches. All three drivers (radial, focus and sledge) contain a digital notch filter as described. Each driver has its own power supply pins to reduce crosstalk because of the relative high current flowing through the pins.





#### Switches

The digital part of the power drivers consists of standard cells. The power switches are specifically designed for CD applications. The most important feature is their on-resistance. In the applications, they have to drive very low-ohmic actuators and/or motors. The switches are designed to have an on-resistance of 2  $\Omega$  for the actuator drivers and 1  $\Omega$  for the sledge motor driver. In any mode, there are always two switches in series with the actuator/motor. The total loss due to the switches is 4  $\Omega$  for the actuators and 2  $\Omega$  for the sledge motor.

### Timing of input and output signals

All internal timing signals are derived from the externally supplied CLI signal.

Sampling of the data inputs (SLC, FOC and RAC) occurs at a frequency of  $\frac{1}{4}$ CL. For each channel, the clocking-in occurs at a different positive edge of CLI. Because there are only 3 channels, and the clock frequency CLI is divided-by-4, only 3 out of 4 positive edges are effective for sampling one of the inputs.

The switching of the outputs occurs in a similar way, except that in this event the negative edge of CLI is used. In this way, the input signals are immune to the noise radiated by the switching of the outputs. It is possible that an output transition will have a noticeable effect on the power supply voltage or the ground voltage. To avoid simultaneous transitions of all outputs, the outputs of each bridge are also clocked at a different phase of CLI. Consequentially there are only 3 out of 4 negative edges effective.

Fig.8 Idling pattern.

TIMING

To reset the circuit, both the reset condition and the clock should be present, because all flip-flops are reset synchronously. The clock signal is also required to obtain one of the possible modes of operation indicated in Table 1.

### OQ8844

VDD

М

lidle

Vss

С

в

(1)

D

OQ8844

EN1	EN2	SLEDGE DRIVER	FOCUS/RADIAL DRIVER	MODE
0	0	off	off standby	
0	1	off	on partly operating	
1	0	off	off	reset
1	1	on	on operating	

 Table 1
 Possible modes of operation

The timing diagram as shown in Fig.9 gives the relation between the different clocks.

The negative edge of the signals called nc10 to nc12 is used to process the incoming data (see Table 2).

The negative edge of all signals called c10s to c12s is used to trigger the outputs (see Table 2).

 Table 2
 Signals nc10 to nc12 and c10s to c12s

SIGNAL	DESCRIPTION
ncl0	sledge input sampling clock
ncl1	focus input sampling clock
ncl2	radial input sampling clock
cl0s	sledge output trigger clock
cl1s	focus output trigger clock
cl2s	radial output trigger clock

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V <sub>DDD</sub>	digital supply voltage	-0.5	+6.5	V
V <sub>DDA</sub>	analog supply voltage	-0.5	+6.5	V
$V_{SSD} - V_{SSA}$	ground supply voltage difference	-5	+5	mV
P <sub>tot</sub>	total power dissipation	_	730	mW
T <sub>stg</sub>	storage temperature	-55	+150	°C
T <sub>amb</sub>	operating ambient temperature	-40	+85	°C

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient in free air	75	K/W

OQ8844

### CHARACTERISTICS

 $V_{DDD}$  =  $V_{DDA}$  = 5 V;  $V_{SSD}$  =  $V_{SSA}$  = 0 V;  $T_{amb}$  = 25 °C; unless otherwise specified.

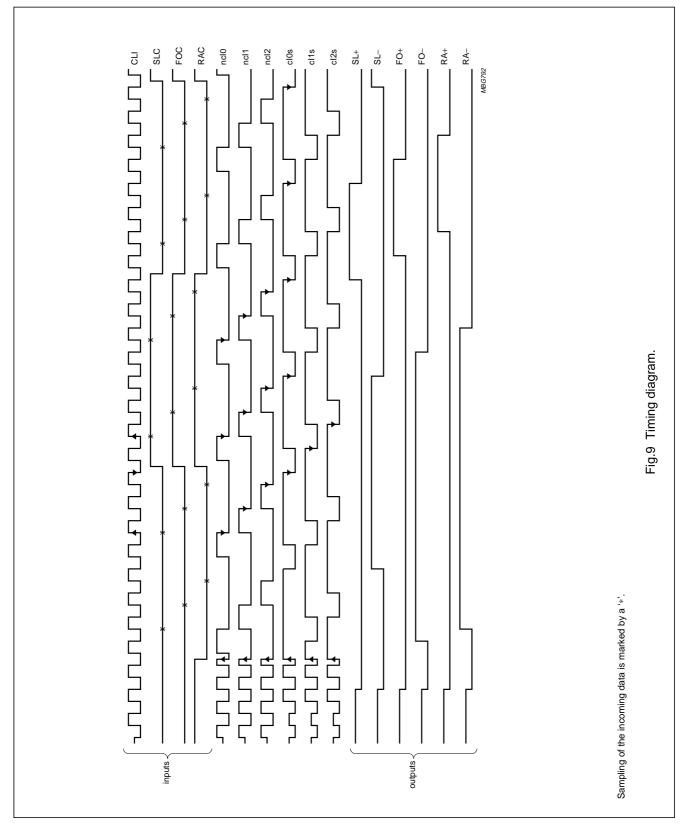
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>DDD</sub>	supply voltage digital part		4.5	-	5.5	V
V <sub>DDA</sub>	supply voltage analog part		4.5	-	5.5	V
I <sub>DDDq</sub>	quiescent supply current digital part		-	-	10	μA
I <sub>DD(F)max</sub>	maximum supply current focus	note 1	-	126	250	mA
I <sub>DD(R)max</sub>	maximum supply current radial	note 1	-	20	250	mA
I <sub>DD(S)max</sub>	maximum supply current sledge	note 1	-	150	560	mA
f <sub>i(clk)</sub>	input clock frequency		-	4.2336	5	MHz
P <sub>tot</sub>	totalpower dissipation		-	110	-	mW
T <sub>amb</sub>	operating ambient temperature		-40	-	+85	°C
Digital inpu	ts; SLC, FOC, RAC, CLI, EN1 and	EN2		•	•	
V <sub>IL</sub>	LOW level input voltage	$T_{amb} = -40$ to 85 °C	_	-	$0.2V_{DDD}$	V
V <sub>IH</sub>	HIGH level input voltage	$T_{amb} = -40$ to 85 °C	0.8V <sub>DDD</sub>	-	-	V
ILI	input leakage current		-	-	1	μA
Clock input	; CLI		·	•		•
f <sub>clk</sub>	clock frequency		-	4.2336	5	MHz
Analog out	outs; FO+ and FO-			-	-	•
lo	output current		-	-	250	mA
R <sub>O</sub>	output resistance	note 2	-	3.3	4.1	Ω
Analog out	buts; RA+ and RA-	1	-	•	-	-
lo	output current		_	_	250	mA
R <sub>O</sub>	output resistance	note 2	-	3.7	4.6	Ω
Analog out	outs; SL+ and SL-		1	1	1	
I <sub>O</sub>	output current		-	-	560	mA
R <sub>O</sub>	output resistance	note 2	-	2.5	3.1	Ω

#### Notes

1. Maximum supply current depends on the value of R<sub>L</sub>:  $I_{max} = \frac{V_{DDA max}}{(R_O + R_L)}$ 

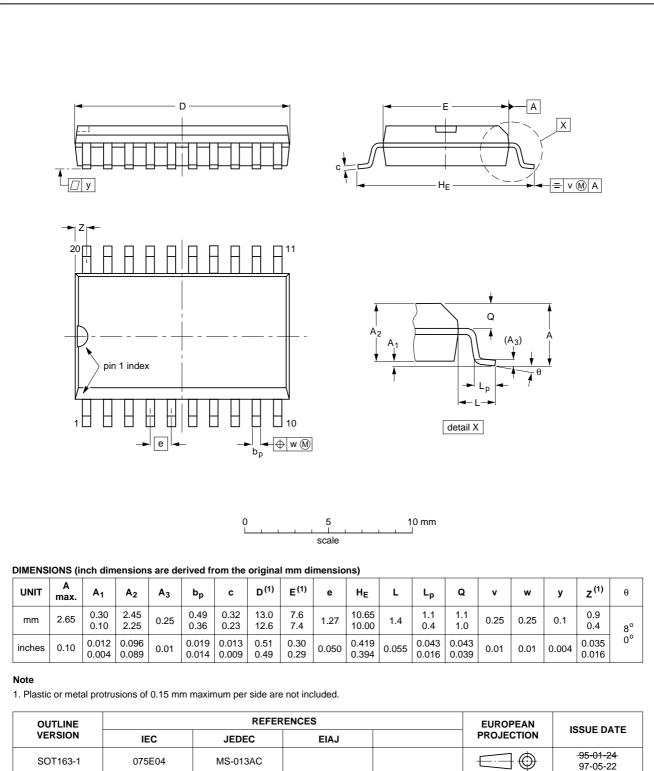
2. Output resistance is defined as the series resistance of the complete bridge.

### **Timing diagram**



### PACKAGE OUTLINE

### SO20: plastic small outline package; 20 leads; body width 7.5 mm



SOT163-1

### OQ8844

### SOLDERING

### Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

### **Reflow soldering**

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

### Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

#### **Repairing soldered joints**

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

# Product specification

### OQ8844

### DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
more of the limiting values r of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or nay cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification imiting values for extended periods may affect device reliability.
Application information	

Where application information is given, it is advisory and does not form part of the specification.

### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

OQ8844

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OQ8844

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Printed in The Netherlands

513061/50/01/pp16 Document order number: Date of release: 1995 Nov 27 9397 750 00471

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